

**molex® 2.54mm (.100") Pitch
DIN 41612
Header**

- Sizes 48 and 96 circuits
- Face mount for wave soldering applications
- DIN 41612 and IEC 603-2 compatible
- Two points of contact provide low insertion force and reliable connection

Product Specification: PS-53296/PS-53320
Packaging: Tray
UL File No.: E29179 (for 53296 only)
CSA File No.: LR19980
Mates With: 52302 and 52480
Designed In: Millimeters

Voltage: 300V
Current: 2.0A
Contact Resistance: 20mΩ max.
Dielectric Withstanding Voltage: 1000V AC
Insulation Resistance: 10⁶ MΩ min.

Housing: Glass-filled PBT, UL 94V-0
Contact: Brass
Metal Peg: Phosphor Bronze
Plating: See Table
Operating Temperature: -55 to +105°C

53296/53320

Triple Row Right Angle

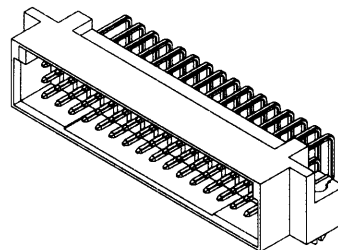
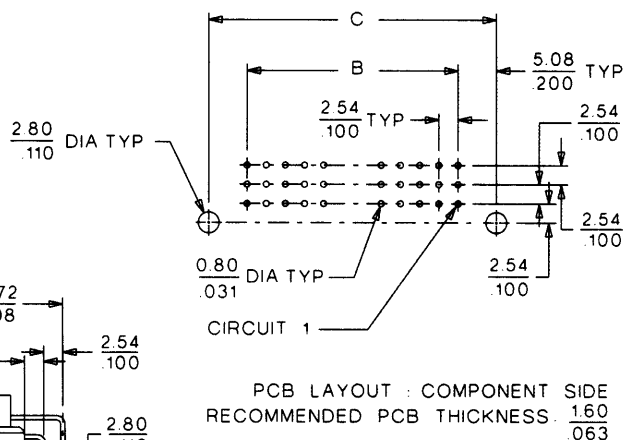


Figure 3 consists of two views of a circuit board. The top view is a plan view showing dimensions A, B, C, and D. A detail shows a spacing of 2.54 TYP / 100. The bottom view is a cross-sectional view showing a thickness of 12.64 / .498. The bottom view also shows a grid of components labeled 'CIRCUIT 1' and a dimension of 10.95 / .431.



Circuits	Order No.		Dimension			
	Without Metal Peg	With Metal Peg	A	B	C	D
48	53296-048X	53320-048X	53.16 (2.093)	38.10 (1.500)	48.26 (1.900)	46.86 (1.845)
96	53296-096X	53320-096X	93.80 (3.693)	78.74 (3.100)	88.90 (3.500)	87.50 (3.445)

Replace X with plating no., 0-3

Plating No. 0: 0.1 μ m Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 1: 0.3 μ m Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 2: 0.5 μ m Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 3: 0.76 μ m Gold with Nickel underplate overall and Tin/Lead in solder area